

	Type	L #	Hits	Search Text
1	BRS	L1	32266 5	(( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )) .ti,ab.
2	BRS	L2	330	1 and ( skip\$ near7 ( process\$3 or step\$1 or judgement ))
3	BRS	L3	23	1 and ( skip\$ near7 ( process\$3 or step\$1 or judgement ))
4	BRS	L4	307	1 and ( skip\$ near7 ( process\$3 or step\$1 or judgement ))
5	BRS	L5	18	( (( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )) .ti,ab.) and ( skip\$ near7 ( process\$3 or step\$1 ) near7 ( judg\$5 or determin\$3 ))
6	BRS	L6	0	( (( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )) .ti,ab.) and ( skip\$ near7 ( process\$3 or step\$1 ) near7 ( judg\$5 or determin\$3 ))
7	BRS	L7	32282 8	(( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )) .ti,ab.
8	BRS	L8	18	( (( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )) .ti,ab.) and ( skip\$ near7 ( process\$3 or step\$1 ) near7 ( judg\$5 or determin\$3 ))

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	DBs	Time Stamp	C o m m e n t s	E r r o r s
1	USPAT; US-PGPUB ; EPO; JPO; DERWENT	2004/09/08 15:18		0
2	USPAT; US-PGPUB ; EPO; JPO; DERWENT	2004/09/08 15:20		0
3	EPO; JPO; DERWENT	2004/09/08 15:21		0
4	USPAT; US-PGPUB	2004/09/08 15:21		0
5	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:22		0
6	EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:23		0
7	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:24		0
8	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:24		0

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	Type	L #	Hits	Search Text
9	BRS	L9	8	( (( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )).ti,ab.) and (( bypass\$3 or ( by adj pass\$3 )) near7 ( process\$3 or step\$1 ) near7 ( judg\$5 or determin\$3 ))
10	BRS	L10	10	( (( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )).ti,ab.) and (( omit\$5 or omission ) near7 ( process\$3 or step\$1 ) near7 ( judg\$5 or determin\$3 ))
11	BRS	L11	47	( (( semiconductor or wafer\$1 or chip\$1 or ( integrated adj circuit\$3 ) or ic\$2 ) near7 ( fab\$8 or manufactur\$3 or processing )).ti,ab.) and (( eliminat\$4 ) near7 ( process\$3 or step\$1 ) near7 ( judg\$5 or determin\$3 ))

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	DBs	Time Stamp	Errors	Comments
9	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:25	0	
10	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:26	0	
11	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:26	0	

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